

LNJ436W82RA

High Bright Surface Mounting Chip LED

ESS Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|-------------------------------|-----------|-------------|------------------|
| Power dissipation | P_D | 55 | mW |
| Forward current | I_F | 20 | mA |
| Pulse forward current * | I_{FP} | 60 | mA |
| Reverse voltage | V_R | 4 | V |
| Operating ambient temperature | T_{opr} | -30 to +85 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -40 to +100 | $^\circ\text{C}$ |

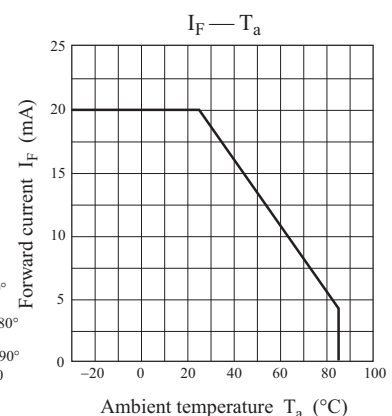
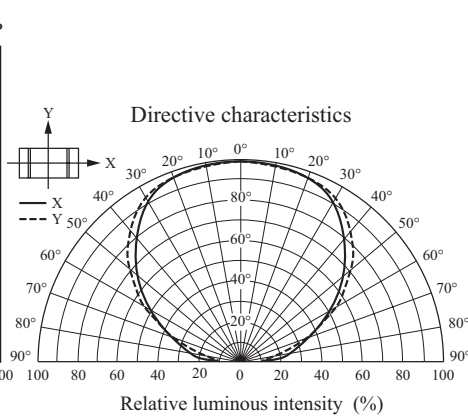
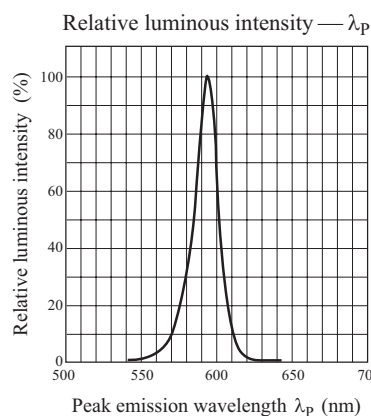
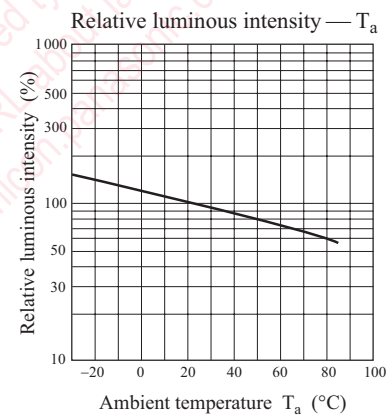
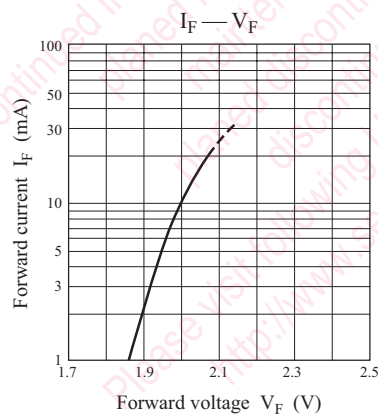
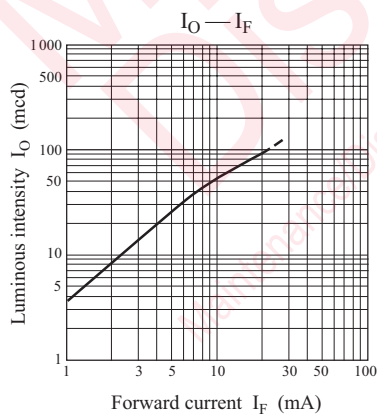
■ Lighting Color

- Amber

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

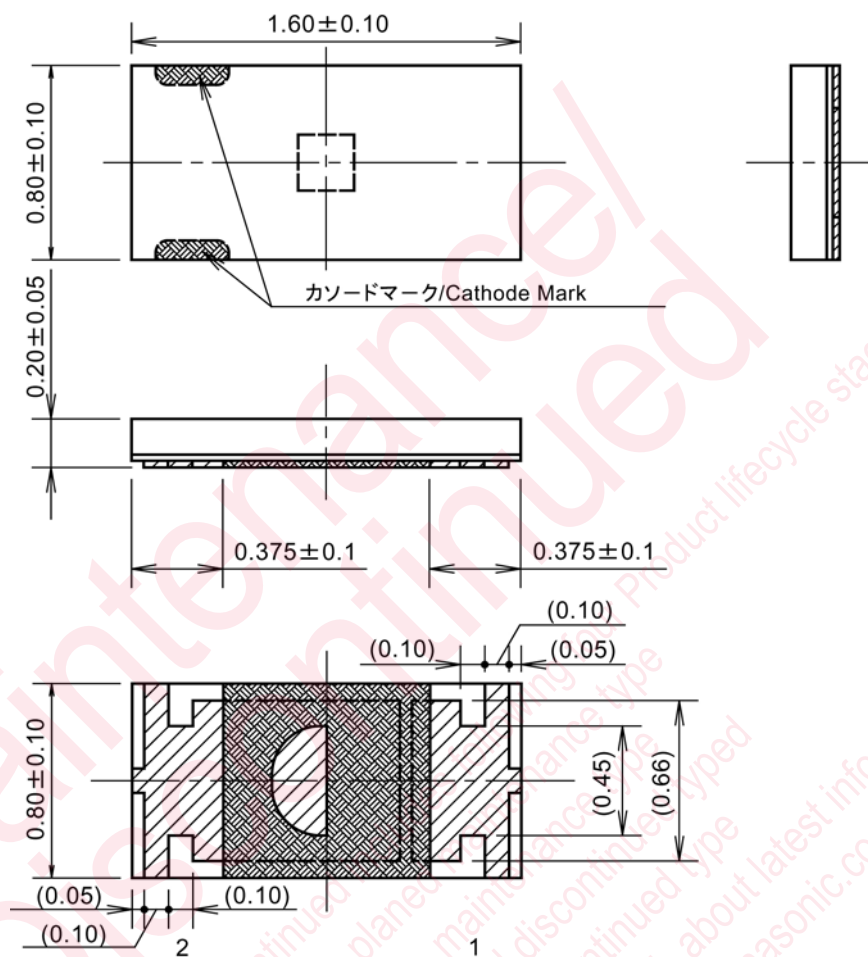
■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---------------------------------|-----------------|----------------------|-----|------|------|---------------|
| Luminous intensity *1 | I_O | $I_F = 5 \text{ mA}$ | 15 | 25 | 45 | mcd |
| Reverse current | I_R | $V_R = 4 \text{ V}$ | | | 100 | μA |
| Forward voltage | V_F | $I_F = 5 \text{ mA}$ | | 1.95 | 2.30 | V |
| Peak emission wavelength | λ_P | $I_F = 5 \text{ mA}$ | | 595 | | nm |
| Dominant emission wavelength *2 | λ_d | $I_F = 5 \text{ mA}$ | 585 | 590 | 595 | nm |
| Spectral half band width | $\Delta\lambda$ | $I_F = 5 \text{ mA}$ | | 15 | | nm |

Note) *1: Measurement tolerance: $\pm 20\%$ *2: Measurement tolerance: $\pm 2 \text{ nm}$ 

■ Package (Unit: mm)

KLTFTN2K3600



- Pin name
1: Anode
2: Cathode

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